

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Kwang-Choon Chung	06/30/2007
Hyun-Nam Cho	06/30/2007
Myoung-Seon Gong	06/30/2007
Yi-Sup Han	06/30/2007
Jeong-Bin Park	06/30/2007
Dong-Hun Nam	06/30/2007
Seong-Yong Uhm	06/30/2007
Young-Kwan Seo	06/30/2007
Nam-Boo Cho	06/30/2007

**RECEIVING PARTY DATA**

Name:	Inktec Co., Ltd.
Street Address:	1124, Shingil-dong, Kyeongki-do
City:	Ansan
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF
Postal Code:	425-839

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	12722689

**CORRESPONDENCE DATA**

Fax Number: (412)945-5933  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
 Phone: 412-471-8815  
 Email: assignments@webblaw.com  
 Correspondent Name: The Webb Law Firm  
 Address Line 1: 436 Seventh Avenue  
 Address Line 2: 700 Koppers Building

OP \$40.00 12722689

Address Line 4: Pittsburgh, PENNSYLVANIA 15219

ATTORNEY DOCKET NUMBER:

5038-100419

NAME OF SUBMITTER:

Richard L. Byrne, Reg. No. 28,498

Total Attachments: 4

source=Assignment#page1.tif

source=Assignment#page2.tif

source=Assignment#page3.tif

source=Assignment#page4.tif

# COPY

## ASSIGNMENT

WHEREAS We,

**CHUNG, Kwang-Choon**

of 502-301 Samsung Shervill, 401-2 Pungdeokcheon-dong, Yongin-city Kyeonggi-do (449-170),

**CHO, Hyun-Nam**

of 807-302 Suri APT., 1151-1 Sanbon-dong, Gunpo-city, Kyeonggi-do (435-040),

**GONG, Myoung-Seon**

of 904 Hyundai 4-cha APT., Ilwon-dong, Kangnam-gu, Seoul-city (135-230),

**HAN, Yi-Sup**

of 503-1402 Dongmun APT., Ilsan-dong, Ilsan-gu, Goyang-city, Kyeonggi-do (411-310),

**PARK, Jeong-Bin**

of 514-207 Jugong 5-cha APT., Gojan-2dong, Danwon-gu, Ansan-city,

Kyeonggi-do (425-722),

**NAM, Dong-Hun**

of 888-14 Doksan-3dong, Keumcheon-gu Seoul-city (153-010),

**UHM, Seong-Yong**

of 119-503 Cheoncheon APT., Cheoncheon-dong, Jangan-gu, Suwon-city,

Kyeonggi-do (440-710),

**SEO, Young-Kwan**

of 104-1516 Dongbo APT., Geomo-dong, Siheung-city, Kyeonggi-do (429-702), and

**CHO, Nam-Boo**

of 106-1204 Indeokwon Daewoo APT., Pyeongchon-dong, Dongan-gu, Anyang-city,

Kyeonggi-do (431-797),

(hereinafter referred to as "ASSIGNORS");

have invented certain new and useful improvements in:

**CONDUCTIVE INKS AND MANUFACTURING METHOD THEREOF**

which claims priority to KR Application No. 10-2005-0018364, filed on 04 March 2005, KR Application No. 10-2005-0023013, filed on 21 March 2005, KR Application No. 10-2005-0031090, filed on 14 April 2005, KR Application No. 10-2005-0034371, filed on 26 April 2005 and for which We are about to file an application for Letters Patent of the United States;


AND WHEREAS, INKTEC CO., LTD. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Republic of Korea, having a place of business at 1124, Shingil-dong, Ansan-city, Kyeongki-do (425-839), is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behalf of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like

so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: June 30, 2007



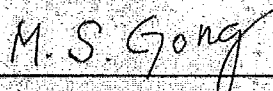
CHUNG, Kwang-Choon

Date: June 30, 2007



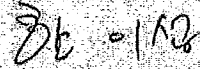
CHO, Hyun-Nam

Date: June 30, 2007



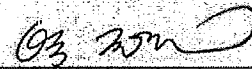
GONG, Myoung-Seon

Date: June 30, 2007



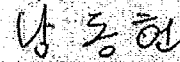
HAN, Yi-Sup

Date: June 30, 2007



PARK, Jeong-Bin

Date: June 30, 2007



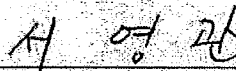
NAM, Dong-Hun

Date: June 30, 2007



UHM, Seong-Yong

Date: June 30, 2007



SEO, Young-Kwan

Date: June 30, 2007



CHO, Nam-Boo